

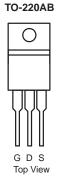
N-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$V_{DS}(V)$ $R_{DS(on)}(\Omega)$			
200	0.270 at V _{GS} = 10 V	10		

FEATURES

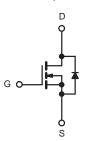
- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC





APPLICATIONS

Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	200	V		
Gate-Source Voltage		V _{GS}	± 20			
Continuous Drain Current /T 475 °C\b	T _C = 25 °C	1	10			
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 125 °C	l _D	6			
Pulsed Drain Current		I _{DM}	38	А		
Continuous Source Current (Diode Conduction)	I _S	12				
Avalanche Current	I _{AS}	10				
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	18	mJ		
Maximum Power Dissipation	T _C = 25 °C	PD	121 ^b	W		
iviaximum rowei Dissipation	T _A = 25 °C	'D	2 ^a] "		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
lungting to Ameliant	t ≤ 10 s	- R _{thJA}	15	18	°C/W	
Junction-to-Ambient ^a	Steady State		40	50		
Junction-to-Case (Drain)		R _{thJC}	0.85	1.1		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.

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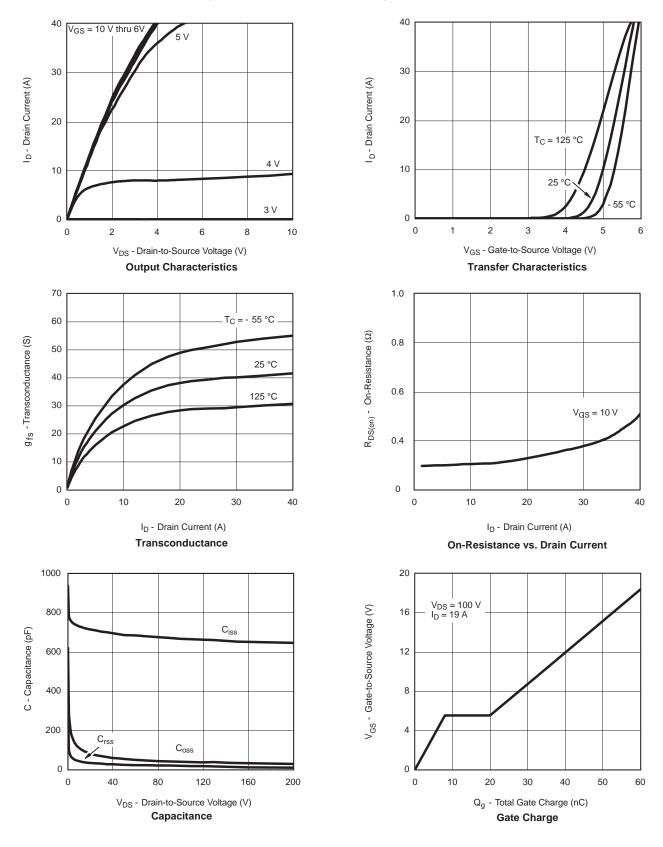
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$			4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 200 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C			50 μA		
		V _{DS} = 200 V, V _{GS} = 0 V, T _J = 175 °C			250	1	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	40			А	
		V _{GS} = 10 V, I _D = 5 A		0.270			
D : 0	D	V _{GS} = 10 V, I _D = 5 A, T _J = 125 °C		0.320		Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 5 A, T _J = 175 °C		0.410			
		$V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$		0.310			
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 19 A		35		S	
Dynamic ^a							
Input Capacitance	C _{iss}			800		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		110			
Reverse Transfer Capacitance	C _{rss}			80			
Total Gate Charge ^c	Q_g			30			
Gate-Source Charge ^c	Q _{gs}	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 19 A		8		nC	
Gate-Drain Charge ^c	Q_{gd}			12			
Gate Resistance	R _g		0.5		2.9	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_{L} = 5.2 \Omega$		50	75		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 19 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45	ns	
Fall Time ^c	t _f			60	90		
Source-Drain Diode Ratings and Char	acteristics (7	Γ _C = 25 °C)					
Pulsed Current	I _{SM}				40	Α	
Diode Forward Voltage ^b	V_{SD}	I _F = 19 A, V _{GS} = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 19 A, dl/dt = 100 A/μs		180	250	ns	

- a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width $\leq 300~\mu s$, duty cycle $\leq 2~\%$. c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

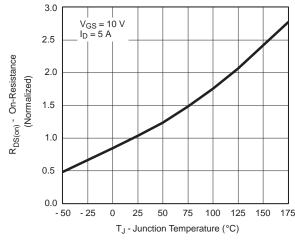


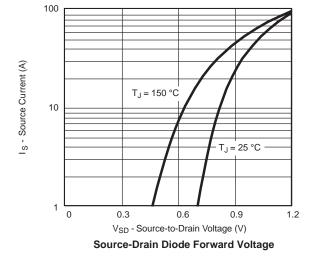
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





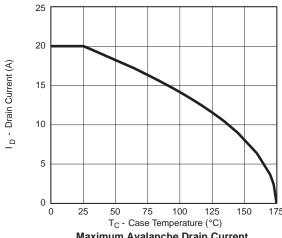
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





On-Resistance vs. Junction Temperature

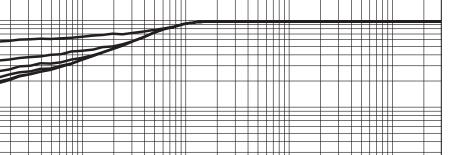
THERMAL RATINGS



100 10 µs 10 I_D - Drain Current (A) T_C = 25 °C Single Pulse 1 s, DC 0.1 L 0.1 10 100 1000 $V_{\rm DS}$ - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{\text{DS(on)}}$ is specified

Safe Operating Area

Maximum Avalanche Drain Current vs. Case Temperature



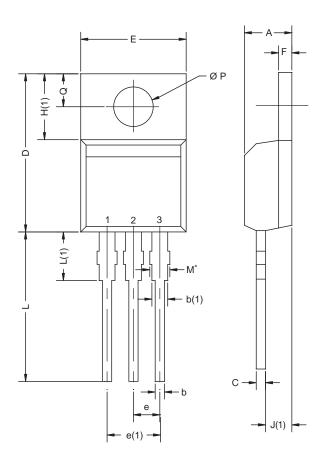
2 Duty Cycle = 0.5 0.2 0.1 0.1 Single Pulse 0.01 10-4 10 30 10-3 Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

Normalized Effective Transient Thermal Impedance



TO-220AB



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM



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